

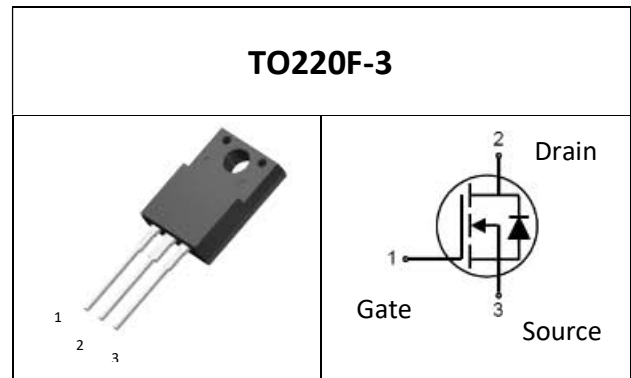
NW6516CW1-3

650V Silicon Carbide Mosfet

Parameter	Value	Unit
V_{DSS}	650	V
$R_{DS(on)}(V_{GS}=15V)$	160	$m\Omega$
$R_{DS(on)}(V_{GS}=18V)$	119	$m\Omega$
$I_D (T_C = 25^\circ C)$	20	A

Features

- High-speed switching with low capacitances
- High blocking voltage with low on-resistance
- Low on-resistance with high junction temperature
- Fast intrinsic diode with low reverse recovery (Q_{rr})
- RoHS Compliant



Applications

- PC Power
- LED Ligh
- EV Charging
- Server Power / Telecom Power
- Solar PV inverters / UPS

Description

The NW6516CW1-3 is a 650 V, SiC mosfet based on NovaWave's advanced SiC technology resulting in high performance and long-term reliability. It supports high-temperature operation while showing minimal losses , zero reverse recovery, and low leakage current.

Pin1-Gate

Pin2-Drain

Pin3-Source

Pin Description

Part Number	Package	Marking
NW6516CW1-3	TO220F-3	NW6516CW1-3

Absolute Maximum Ratings

$T_J = 25^\circ\text{C}$ except as noted. Exceeding the maximum ratings may damage the device.

Parameter	Symbol	Value	Unit	Test conditions
Drain-Source Voltage	$V_{DSS\ max}$	650	V	Static
Continuous Drain Current, limited by $T_{vj(max)}$	I_D	23	A	$V_{GS} = 18\text{ V}, T_C = 25^\circ\text{C}$
		16		$V_{GS} = 18\text{ V}, T_C = 100^\circ\text{C}$
		20		$V_{GS} = 15\text{ V}, T_C = 25^\circ\text{C}$
		14		$V_{GS} = 15\text{ V}, T_C = 100^\circ\text{C}$
Pulse Drain Current, Pulse width t_p limited by $T_{vj(max)}$	$I_{D(pulse)}$	34	A	$V_{GS} = 15\text{ V}, T_C = 25^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	33	mJ	$I_D = 11.5\text{ A}, V_{DS} = 50\text{ V},$ $L = 0.5\text{ mH}, V_{GS} = 15\text{ V}$
Power Dissipation	P_D	69	W	$T_C = 25^\circ\text{C}$
		35		$T_C = 100^\circ\text{C}$
Maximum Gate Source Voltage,transient voltage	V_{GSmax}	-10 to +22	V	
Recommended turn-on Gate Source Voltage	$V_{GS(on)}$	15 to +18	V	
Recommended turn-off Gate Source Voltage	$V_{GS(off)}$	-4 to 0	V	
Storage Temperature Range	T_{stg}	-55 to +175	$^\circ\text{C}$	
Soldering Temperature	T_L	260	$^\circ\text{C}$	
Virtual junction temperature	T_{VJ}	-55 to +175	$^\circ\text{C}$	

*Gate-source transient voltage, $t_p < 1\ \mu\text{s}$, $t \leq 10$ hours over lifetime, -10/+22V.

* T_{VJ} = Virtual Junction Temperature, equivalent to Junction Temperature for device rating and characterization.

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	--	2.16	--	$^{\circ}\text{C/W}$

Electrical Characteristics (at $T_{VJ} = 25^{\circ}\text{C}$, unless otherwise specified)

Parameters	Symbol	Min	Typ	Max	Unit	Condition
Drain-Source Breakdown Voltage	BV_{DSS}	800	--	--	V	$I_D=100\mu\text{A}$, $V_{GS}=0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}	--	0.1	20	μA	$V_{DS} = 650\text{V}$, $V_{GS} = 0\text{V}$, $T_{VJ}=25^{\circ}\text{C}$
		--	1	--		$V_{DS} = 650\text{V}$, $V_{GS} = 0\text{V}$, $T_{VJ}=175^{\circ}\text{C}$
Gate-Source Leakage Current	I_{GSS}	--	--	250	nA	$V_{GS}=22\text{V}$
Gate Threshold Voltage	$V_{GS(th)}$	--	3.9	--	V	$V_{DS}=V_{GS}$, $I_D=10\text{mA}$
		--	2.8	--		$V_{DS}=V_{GS}$, $I_D=10\text{mA}$, $T_{VJ}=175^{\circ}\text{C}$
Drain-Source On-State Resistance	$R_{DS(on)}$	--	160	--	$\text{m}\Omega$	$V_{GS}=15\text{V}$, $I_D=7\text{A}$
		--	164	--		$V_{GS}=15\text{V}$, $I_D=7\text{A}$, $T_{VJ}=175^{\circ}\text{C}$
		--	119	--		$V_{GS}=18\text{V}$, $I_D=7\text{A}$
		--	148	--		$V_{GS}=18\text{V}$, $I_D=7\text{A}$, $T_{VJ}=175^{\circ}\text{C}$
Transconductance	g_{fs}	--	5	--	S	$V_{DS}=20\text{V}$, $I_D=7\text{A}$
Input Capacitance	C_{iss}	--	429	--	pF	$V_{DS}=650\text{V}$, $f=100\text{KHz}$, $V_{GS}=0\text{V}$
Output Capacitance	C_{oss}	--	32	--		
Reverse Transfer Capacitance	C_{rss}	--	3	--		

Internal Gate Resistance	$R_{G(int)}$	--	29	--	Ω	$f=1\text{MHz}, V_{AC}=25\text{mV}, V_{DS}=0\text{V}$	
Total Gate Charge	Q_g	--	14.8	--	nC	$V_{DS}=400\text{V}, I_D=7\text{A}, V_{GS}=0\text{V}/+15\text{V}$	
Gate to Source Charge	Q_{gs}	--	5.3	--			
Gate to Drain Charge	Q_{gd}	--	2.2	--			
Turn-On Delay Time	$t_{d(on)}$	--	29.2	--	ns	$V_{DS}=400\text{V}, I_D=7\text{A},$ $V_{GS}=0\text{V}/+18\text{V},$ $R_{G(ext)}=2.2\Omega,$ $L=600\mu\text{H},$ $T_{VJ}=25^{\circ}\text{C}$ FWD = Body Diode	
Rise Time	t_r	--	11.7	--			
Turn-Off Delay Time	$t_{d(off)}$	--	46.1	--			
Fall Time	t_f	--	16.5	--			
Turn-On Switching Loss	E_{on}	--	67.8	--	μJ		
Turn-Off Switching Loss	E_{off}	--	15.0	--			
Total switching energy	E_{Total}	--	82.8	--			
Turn-On Delay Time	$t_{d(on)}$	--	27.6	--	ns		$V_{DS}=400\text{V}, I_D=7\text{A},$ $V_{GS}=0\text{V}/+18\text{V},$ $R_{G(ext)}=2.2\Omega,$ $L=600\mu\text{H},$ $T_{VJ}=175^{\circ}\text{C}$ FWD = Body Diode
Rise Time	t_r	--	10.8	--			
Turn-Off Delay Time	$t_{d(off)}$	--	43.1	--			
Fall Time	t_f	--	13.3	--			
Turn-On Switching Loss	E_{on}	--	67.5	--	μJ		
Turn-Off Switching Loss	E_{off}	--	10.5	--			
Total switching energy	E_{Total}	--	78.0	--			

Body Diode Characteristics(at $T_{VJ}= 25^{\circ}\text{C}$, unless otherwise specified)

Parameters	Symbol	Min	Typ	Max	Unit	Condition
Diode Forward Voltage	V_{SD}	--	3.3	--	V	$V_{GS}=0V, I_S=3.5A, T_{VJ}=25^{\circ}\text{C}$
		--	2.8	--		$V_{GS}=0V, I_S=3.5A, T_{VJ}=175^{\circ}\text{C}$
Continuous Diode Forward Current	I_S	--	--	23	A	$V_{GS}=-4V$
Diode pulse Current	$I_{S(pulse)}$	--	--	34	A	Pulse width t_p , limited by T_{VJmax}
Reverse Recovery Time	t_{rr}	--	26	--	ns	$V_{GS}=0V, I_D=7A,$ $V_{DS}=400V,$ $di/dt=2A/ns,$ $T_{VJ}=25^{\circ}\text{C}$
Reverse Recovery Charge	Q_{rr}	--	68	--	nC	
Peak Reverse Recovery Current	I_{rrm}	--	6.9	--	A	
Reverse Recovery Time	t_{rr}	--	27	--		$V_{GS}=0V, I_D=7A,$ $V_{DS}=400V,$ $di/dt=2A/ns,$ $T_{VJ}=175^{\circ}\text{C}$
Reverse Recovery Charge	Q_{rr}	--	82	--		
Peak Reverse Recovery Current	I_{rrm}	--	5.8	--		

Electrical Performance Graphs

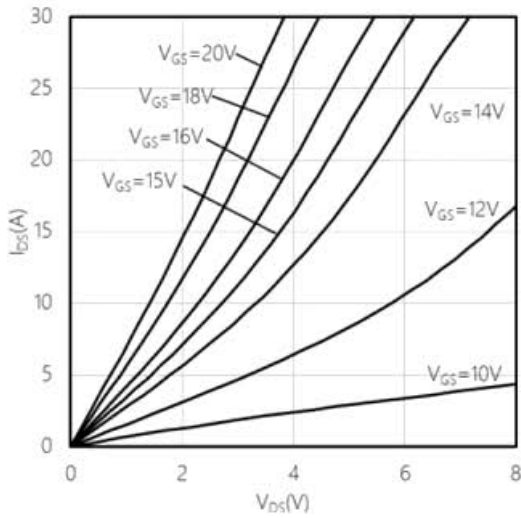


Figure 1: Typical Output Characteristics
 $T_{VJ} = -55^{\circ}\text{C}$

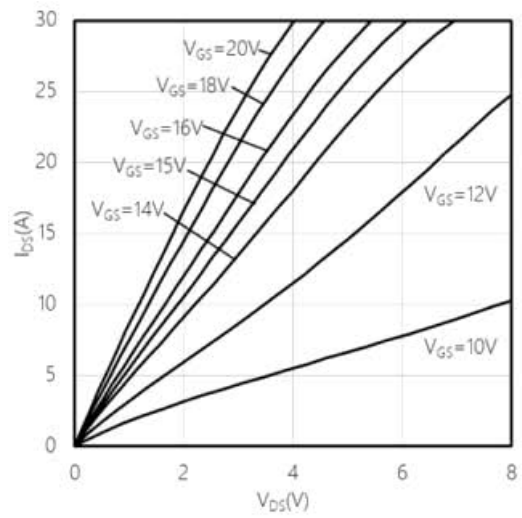


Figure 2: Typical Output Characteristics
 $T_{VJ} = 25^{\circ}\text{C}$

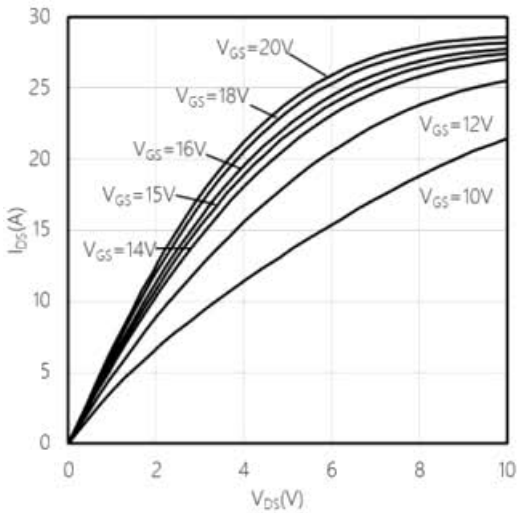


Figure 3: Typical Output Characteristics
 $T_{VJ} = 175^{\circ}\text{C}$

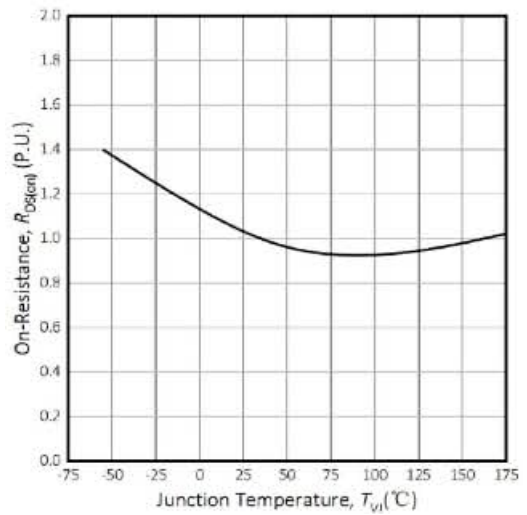


Figure 4: Normalized On-Resistance vs. Temperature
 $I_D = 7\text{ A}$, $V_{GS} = 15\text{ V}$

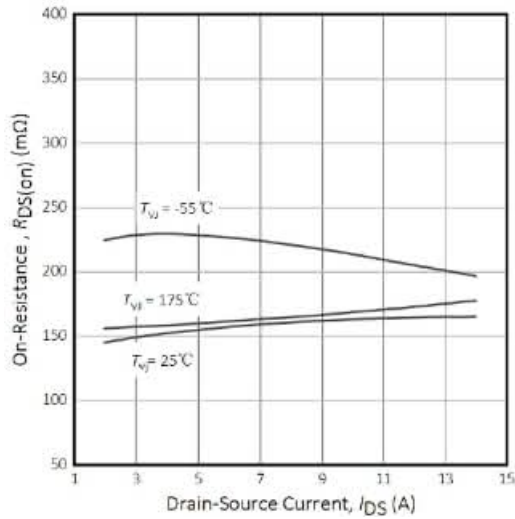


Figure 5: On-Resistance vs. Drain Current for Various Temperature $V_{GS} = 15\text{ V}$

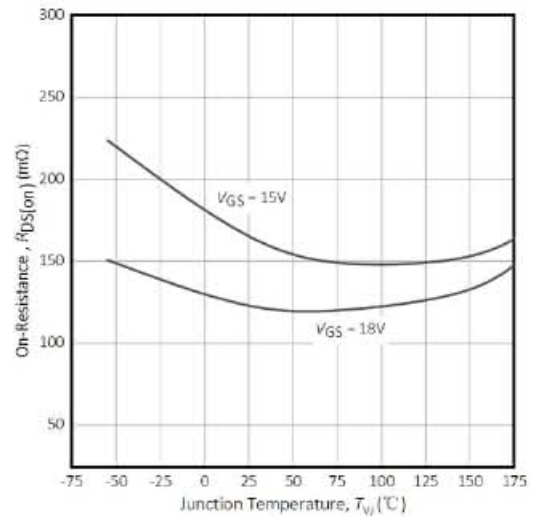


Figure 6: On-Resistance vs. Junction Temperature for Various Gate Voltage $I_D = 7\text{ A}$

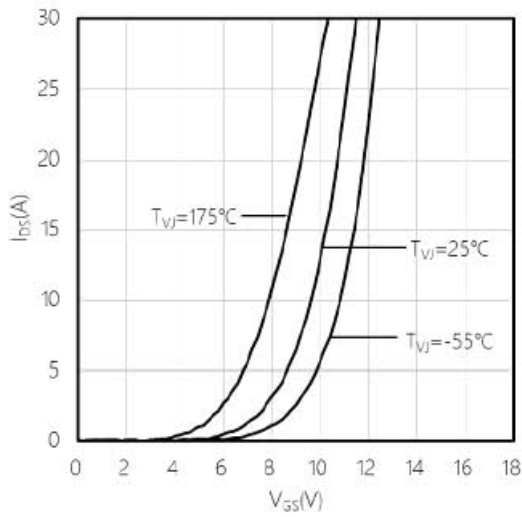


Figure 7: Transfer Characteristic for Various Temperature $V_{DS} = 20\text{ V}$

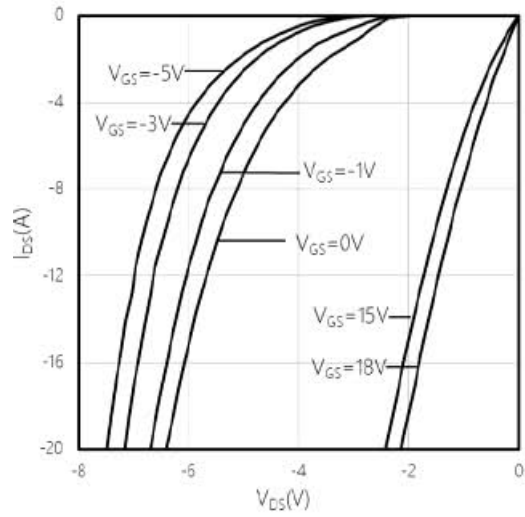


Figure 8: Typical 3rd Quadrant Characteristics $T_{VJ} = -55^\circ\text{C}$

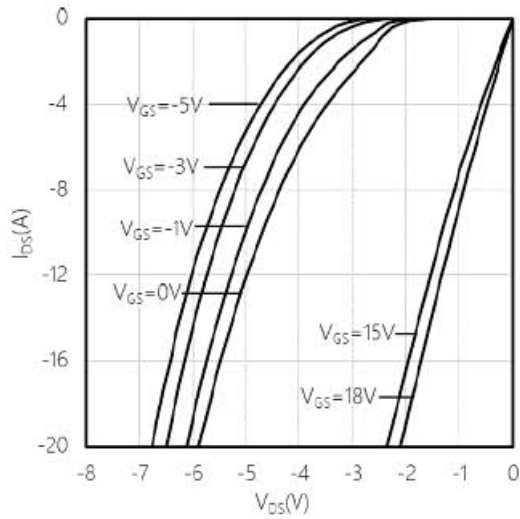


Figure 9. Typical 3rd Quadrant Characteristics
 $T_{VJ}=25^{\circ}\text{C}$

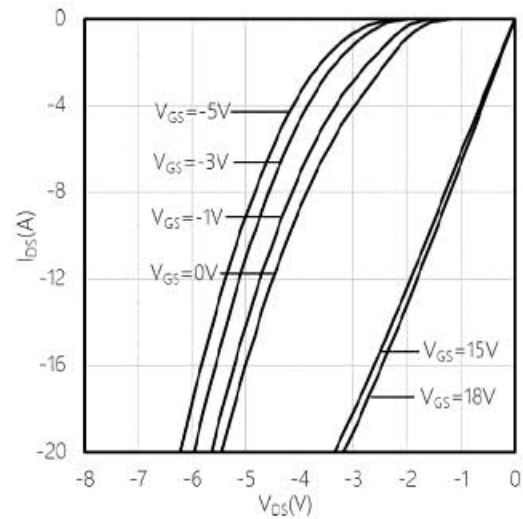


Figure 10. Typical 3rd Quadrant Characteristics
 $T_{VJ}=175^{\circ}\text{C}$

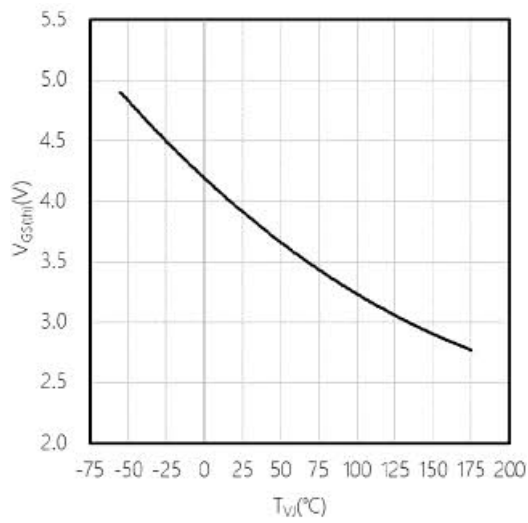


Figure 11. Threshold Voltage vs. Temperature
 $V_{GS} = V_{DS}$, $I_D = 10 \text{ mA}$

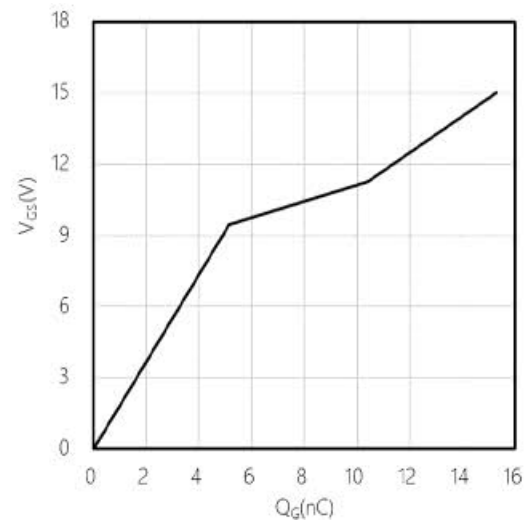


Figure 12. Gate Charge Characteristics
 $V_{DS} = 400\text{V}$, $T_{VJ} = 25^{\circ}\text{C}$

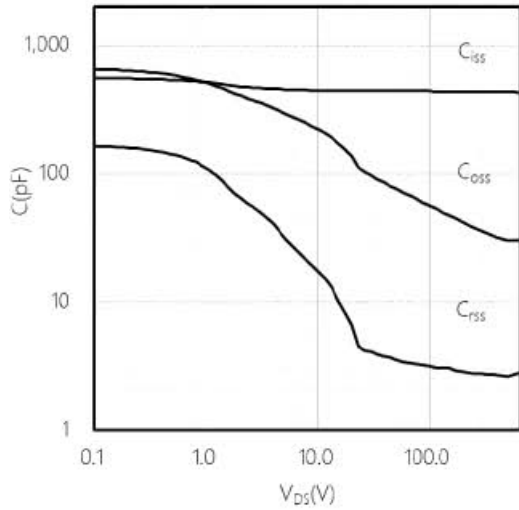


Figure 13: Typical Capacitances vs. Drain-Source Voltage (0 – 650V)
 $T_{vj} = 25^{\circ}\text{C}$, $V_{AC} = 25 \text{ mV}$, $f = 100 \text{ KHz}$

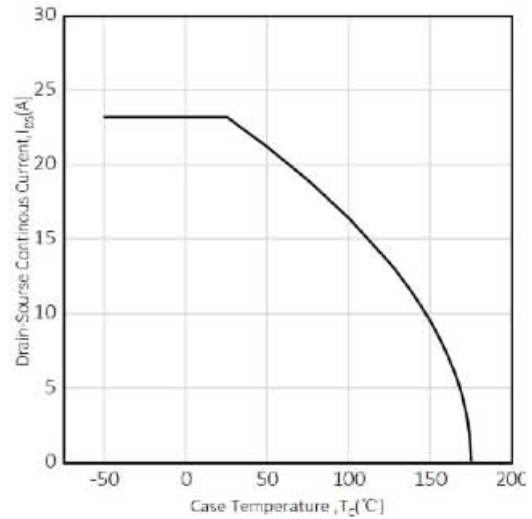


Figure 14: Continuous Drain Current Derating vs. Case Temperature $T_{vj} \leq 175^{\circ}\text{C}$

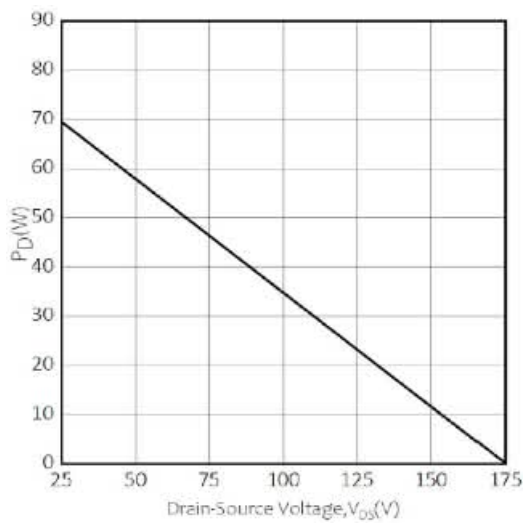


Figure 15: Maximum Power Dissipation Derating vs. Case Temperature $T_{vj} \leq 175^{\circ}\text{C}$

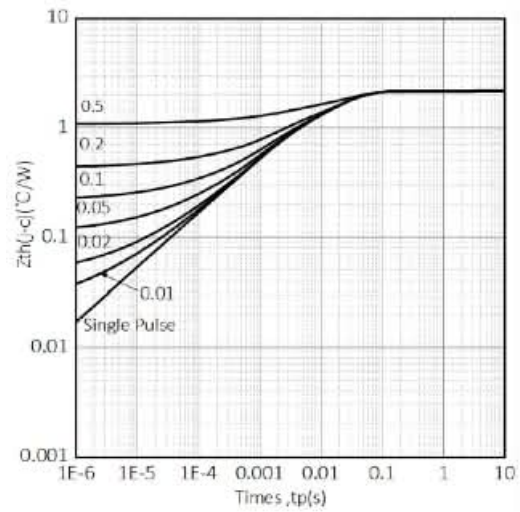


Figure 16: Transient Thermal Impedance (Junction-Case) with Different Duty Cycle

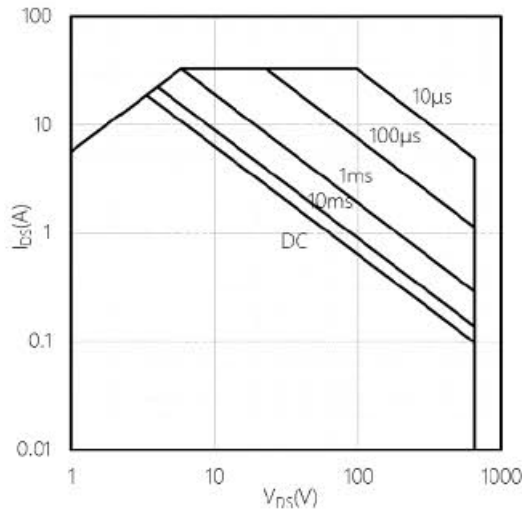


Figure 17: Safe Operating Area

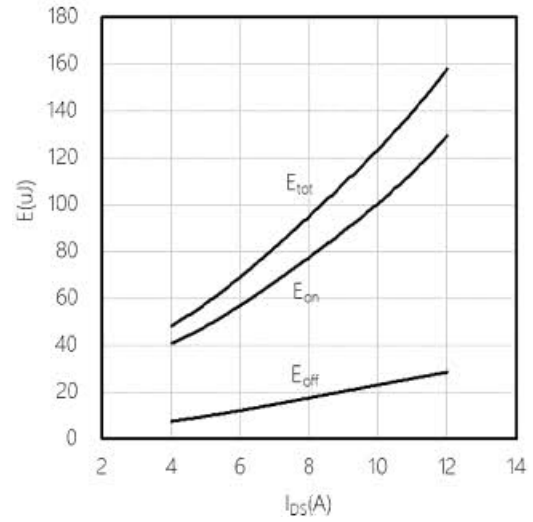


Figure 18: Clamped Inductive Switching Energy vs. Drain Current

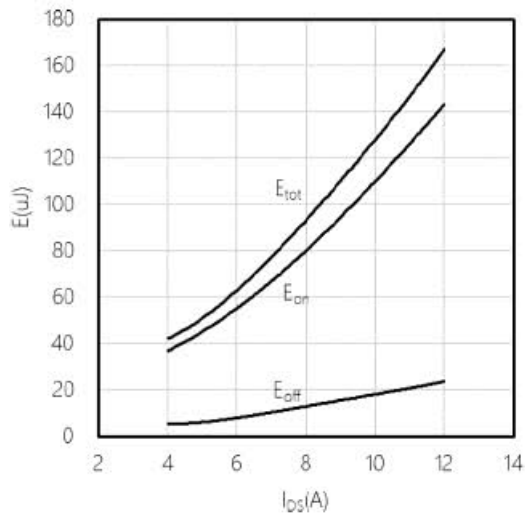


Figure 19: Clamped Inductive Switching Energy vs. Drain Current

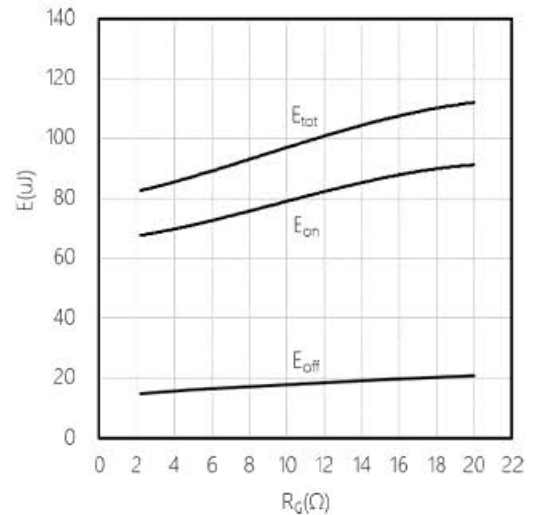


Figure 20: Clamped Inductive Switching Energy vs. $R_{G(ext)}$

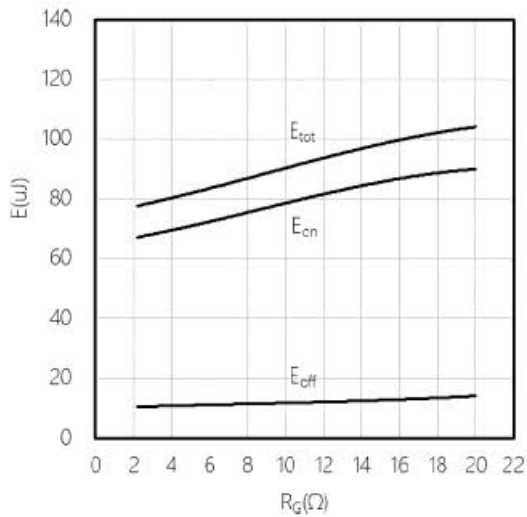


Figure 21: Clamped Inductive Switching Energy vs. $R_{G(ext)}$

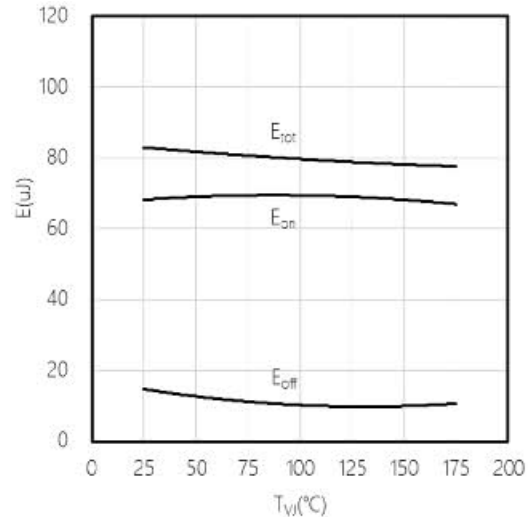


Figure 22: Clamped Inductive Switching Energy vs. Temperature

Testing conditions

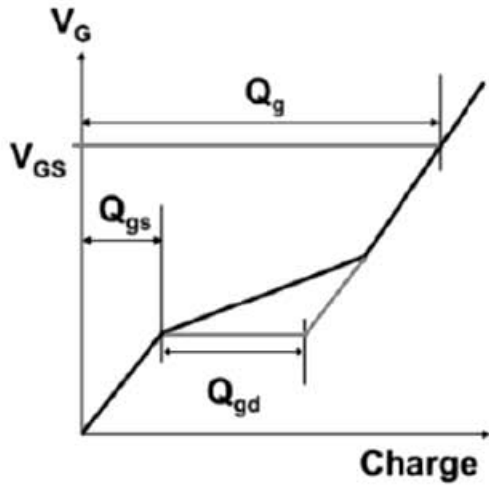


Figure A: Definition of Q_{gd}

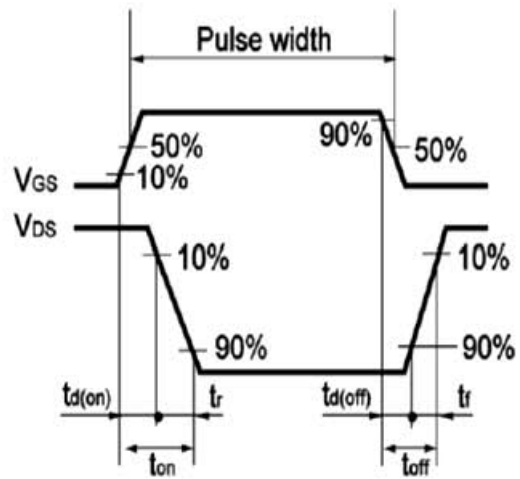


Figure B: Definition of switching times

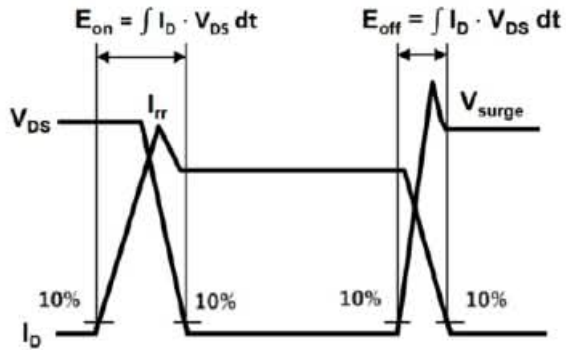


Figure C: Definition of switching losses

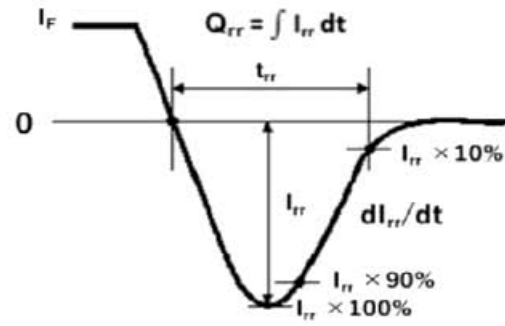
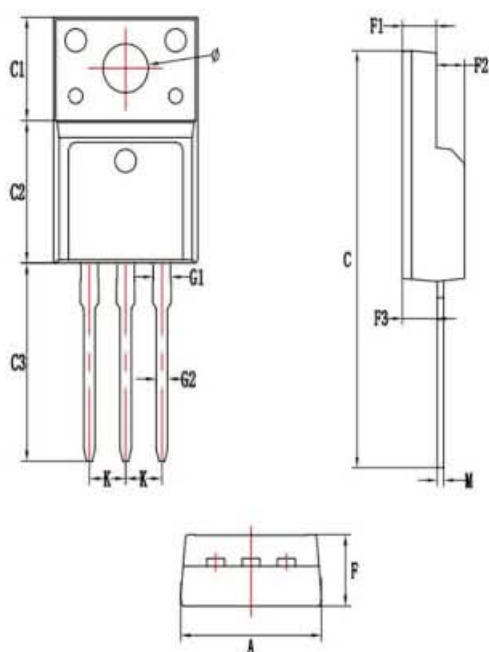


Figure D: Definition of reverse recovery

Package Dimensions



SYMBOL	Unit(mm)	
	Min	Max
A	10.00	10.20
C	28.20	29.00
C1	6.63	6.70
C2	9.17	9.27
C3	12.35	12.95
Ø	3.33	3.43
F	4.45	4.75
F1	2.40	2.60
F2	2.00	2.20
F3	2.30	2.70
G1	1.15	1.25
G2	0.75	0.85
K	2.54	
M	0.45	0.55

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